REMARKS

In response to the Examiner's objection to the title, a new title has been presented as suggested by the Examiner. Additionally, specification page 1, line 2 has been amended to update the parent application. Additionally, the originally filed abstract has been replaced by the enclosed Replacement Abstract which sufficiently describes the claimed method invention. No new matter has been added.

In response to the rejection of Claims 7-10 under 35 USC 112, these claims have been canceled and replaced by newly presented Claims 11-22 which more particularly point out and distinctly claim the subject matter which Applicants regard as the invention. It is respectfully submitted that the newly presented claims contain no formal defects and clearly comply with 35 USC 112. Newly presented Claims 12 and 13 contain the subject matter of objected-to Claims 8 and 9 in independent form. Accordingly, it is respectfully submitted that Claims 12 and 13, and the claims dependent thereon, are allowable.

Claims 7 and 10 have been rejected under 35 USC 103(a) as being unpatentable over Kobayashi et al. Applicants respectfully traverse this ground of rejection and urge reconsideration in light of the following comments.

The present invention, as defined by newly presented independent Claim 11, is directed to a method for manufacturing a multi-layer ceramic electronic part. This method comprises the steps of preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another, forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body by applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body and baking the unbaked laminated body and the external electrodes simultaneously to sinter them.

At the outset, Applicants wish to point out that the Kobayashi et al reference is not available as prior art

against the present application since it has a U.S. filing date of January 13, 2000 and the present application claims an earlier foreign priority date of March 29, 1999. Enclosed herewith are certified English language translations of the foreign priority documents to remove Kobayashi et al as a reference against the present application. Additionally, the currently presented claims require a step of baking the unbaked laminated body and the external electrodes at the same time. By baking the unbaked laminated body and the external electrodes at the same time, the baking of the so-called "common material", which is contained in the external electrodes and the ceramic layers of the laminated body, are baked as one body. Therefore, a strong adhesiveness is provided therebetween. As shown in Column 3, lines 24-30 of the Kobayashi et al reference, the external electrodes are sintered after the baking of the laminated body. As such, it is respectfully submitted that the currently claimed invention is clearly patentably distinguishable over the prior art cited by the Examiner.

The Examiner is respectfully requested to reconsider the present application and to pass it to issue.

Respectfully submitted,

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